| ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INDUSTRIES® INTERNATIONAL AND ADDRESS | Bannockburn, Illir | nois. All rights reserved u | nder both le | This docume evel parts, th | ent is a declarat he declaration of | ion of the sub encompasses a | stances w | ithin the manufactur evel materials for wh | er listed it hich the m | em. Note: if anufacturer l | the item is an as | sembly with lower responsibility. |
|---|---|-----------------------------|----------------|--|--|--|-----------|---|---------------------------------------|-------------------------------|-------------------|---------------------------------------|
| | Web Site for Information on IPC-1752 Standard Form Typ p://www.ipc.org/IPC-175x Distribute | | | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | als and Mfg Information | | | | |
| Supplier Information | | | | | | | | | | | | |
| Company name* | any unique ID | ique ID | | | Unique ID Authority | | | | Response Date* | | | |
| nsemi | | | | | | | | | 2024-09-21 | | | |
| Contact Name | Title - Contact | | | 1 | Phone - Contact* | | | | Email - Contact* | | | |
| Product-Env-Stewards | uct-Env-Stewards Product Enviro Complian | | | N | | NA | | | Product-Env-Stewards@onsemi.com | | | |
| Authorized Representative* | horized Representative* Title - Representative | | | Phone - Representative* | | | | Email - Representative* | | | | |
| Product-Env-Stewards | ct Enviro Compliance | iro Compliance | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | Mfr Item Number | er Mfr Item Name | Mfr Item Name | | Effective Date | Version | Ma | Manufacturing Site | | Veight* | UOM | Unit Type |
| | NCV565D2TR40 | G ANA 1.5A LDO I | EGULATOR | | 2024-09-21 | | MY | MY1 | | 617.9136 | mg | Each |
| Manufacturing Proccess Information | | | | | | | | | | | | · · · · · · · · · · · · · · · · · · · |
| Terminal Plating / Grid Array Materia | 1 Terminal | l Base Alloy J | -STD-020 MSL I | Rating | Peak Proc | rocess Body Temperature Max Time at Pe | | Max Time at Peak | k Temperature Number of Reflow Cycles | | cles | |
| Matte Tin (Sn) - annealed CU Alloy | | y 1 | 1 | | 260 | (| 2 | 30 | second | is 3 | | |
| Comments | | | | | | | | | | | | |
| level 1 - maximum time at peak temperature d | uring soldering i | is 10-30 seconds | | | | | | | | | | |
| For more information regarding material com | position please r | refer to page 3 | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | | |
|--|---|--|--------------|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | (Pb), Mercury (Hg), Hexavalent Chro | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP). | | | | | | | | | |
| Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rot a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itality and the Company's remedies for issues that aris regarding information the Supplier provides in this | | | | | | | | | | | |
| RoHS Declaration * 4 - Item(| s) does not contain RoHS restricted subst | ances per the definition above except for sele | ected exempt | ions Supplier Acceptance | * Accepted | | | | | | |
| Exemption: 7a: Lead in high melting temp | erature type solders (i.e. lead based sol | der alloys containing 85% by weight or m | ore lead). | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | | |
| Declaration Signature | | | | | | | | | | | |
| Instructions: Complete all of the required Requester) and click on Submit Form to h | | | e drop-dowi | a. This will display the signature area. Digita | lly sign the declaration (if required by the | | | | | | |
| Supplier Digital Signature | astislav Drska | Le | | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|----------|-----------------|----------|----------------------------|------------------|--------|----------|-----------------|
| Die | 0.19 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.19 | mg |
| Die Attach | 11.31 | mg | А | Lead (Pb) | 7439-92-1 | 7a | 10.7445 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.5655 | mg |
| Lead Frame | 851.27 | mg | В | Nickel (Ni) | 7440-02-0 | | 2.5538 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 848.7162 | mg |
| Mold Compound-Black | 727.2536 | mg | | Epoxy resin | proprietary data | | 36.3627 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 36.3627 | mg |
| | | | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 14.5451 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 3.6363 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 636.3469 | mg |
| Plating | 27.15 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 27.15 | mg |
| Wire Bond - Cu | 0.74 | mg | Supplier | Copper (Cu) | 7440-50-8 | | 0.74 | mg |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).